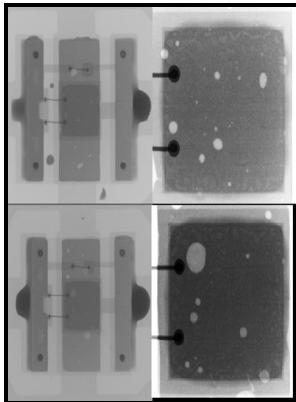


Influence of contamination on the long-term reliability of chip-on-board (COB) technology.

Oxford Brookes University - Thermo



Description: -

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Influence on temperature distribution of COB deep UV LED due to different packaging density and substrate type

Under THB testing, the stencil printable epoxies showed variable behaviour while the UV curable epoxy was average. In COB assembly, bare die are mounted directly on the printed circuit board. Harman lists three references, along with his own comments on the works, that address these problems: Thomas, R.

Thermo

One particularly attractive property of these materials, from the processing viewpoint, is their ability to be cured by means of a relatively short typically 30-60 seconds exposure to blue light.

Evaluation of wire bonding performance, process conditions, and metallurgical integrity of chip on board wire bonds

The stencil printable epoxy had similar cure sensitivity to the standard epoxy, and the UV curable epoxy showed some sensitivity to a 20sec change in cure time. Mostly how contaminants show up in packaging of the ICs. Palomar has COB customers in all industries, particularly aerospace.

Thermo

The silicone encapsulant showed improved results, perhaps due to its stress absorbing low modulus nature. The saving in polymer board or ceramic, silicon, or metal substrate area by having a chip mounted and interconnected directly to it, i. The quantity of resin dispensed in a given time period will depend on the viscosity of the material, diameter of the needle and applied pressure.

Glob top materials to chip on board components

It can also lead to an acceleration of failures due to Al track corrosion mechanisms. However, the voltage levels encountered by glob-top protected power MOSFET devices 300-500V could begin to approach the limit of some glob-top materials if the inter-electrode spacing is small.

Chuck Bauer of TechLead Corp.

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